

L Number	Hits	Search Text	DB	Time stamp
1	57683	metal with wire	USPAT; US-PGPUB	2002/03/13 14:15
2	20507	metal near wire	USPAT; US-PGPUB	2002/03/13 14:15
3	87240	metal same wire	USPAT; US-PGPUB	2002/03/13 14:16
4	87240	(metal with wire) (metal near wire) (metal same wire)	USPAT; US-PGPUB	2002/03/13 10:03
5	41286	((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)	USPAT; US-PGPUB	2002/03/13 14:18
6	5920	((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate))	USPAT; US-PGPUB	2002/03/13 14:18
7	5588	((((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate))) and (via contact hole)	USPAT; US-PGPUB	2002/03/13 14:23
8	4166	((((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate))) and (open\$4 recess trench)	USPAT; US-PGPUB	2002/03/13 14:24
9	5750	((((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate))) and (via contact hole))	USPAT; US-PGPUB	2002/03/13 10:08
10	5561	(((((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate))) and (via contact hole))	USPAT; US-PGPUB	2002/03/13 10:09
11	2649	((((((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate))) and (via contact hole))	USPAT; US-PGPUB	2002/03/13 10:11
12	2613	((((((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate))) and (via contact hole))	USPAT; US-PGPUB	2002/03/13 13:34
14	59257	metal with wire	EPO; JPO; DERWENT; IBM_TDB	2002/03/13 14:17
15	19562	metal near wire	EPO; JPO; DERWENT; IBM_TDB	2002/03/13 14:15
16	73512	metal same wire	EPO; JPO; DERWENT; IBM_TDB	2002/03/13 14:16

17	73512	(metal with wire) (metal near wire) (metal same wire)	EPO; JPO; DERWENT; IBM_TDB	2002/03/13 14:17
18	15788	((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)	EPO; JPO; DERWENT; IBM_TDB	2002/03/13 14:18
19	665	((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate))	EPO; JPO; DERWENT; IBM_TDB	2002/03/13 14:19
20	292	((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate)) and (via contact hole)	EPO; JPO; DERWENT; IBM_TDB	2002/03/13 14:23
21	99	((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate)) and (open\$4 recess trench)	EPO; JPO; DERWENT; IBM_TDB	2002/03/13 14:24
22	340	((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate)) and (via contact hole)) (((metal with wire) (metal near wire) (metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice substrate)) and (open\$4 recess trench))	EPO; JPO; DERWENT; IBM_TDB	2002/03/13 14:25